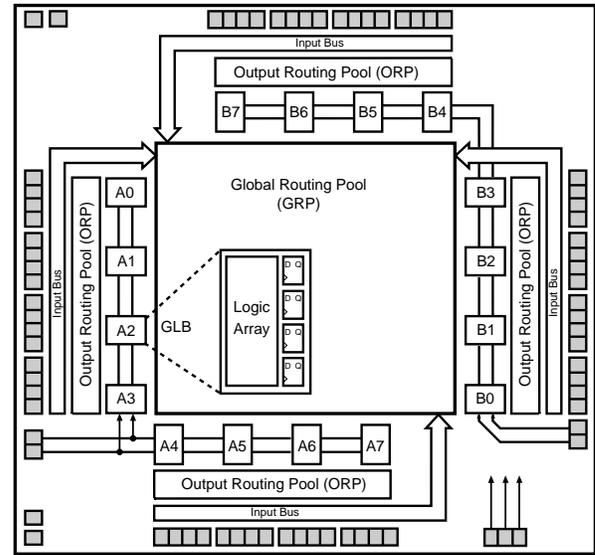


Features

- **HIGH DENSITY PROGRAMMABLE LOGIC**
 - 2000 PLD Gates
 - 64 I/O Pins, Four Dedicated Inputs
 - 64 Registers
 - High Speed Global Interconnect
 - Wide Input Gating for Fast Counters, State Machines, Address Decoders, etc.
 - Small Logic Block Size for Random Logic
- **HIGH PERFORMANCE E²CMOS[®] TECHNOLOGY**
 - $f_{max} = 125$ MHz Maximum Operating Frequency
 - $t_{pd} = 7.5$ ns Propagation Delay
 - TTL Compatible Inputs and Outputs
 - Electrically Erasable and Reprogrammable
 - Non-Volatile
 - 100% Tested at Time of Manufacture
 - Unused Product Term Shutdown Saves Power
- **ispLSI OFFERS THE FOLLOWING ADDED FEATURES**
 - In-System ProgrammableTM (ISPTM) 5-Volt Only
 - Increased Manufacturing Yields, Reduced Time-to-Market and Improved Product Quality
 - Reprogram Soldered Devices for Faster Prototyping
- **OFFERS THE EASE OF USE AND FAST SYSTEM SPEED OF PLDs WITH THE DENSITY AND FLEXIBILITY OF FIELD PROGRAMMABLE GATE ARRAYS**
 - Complete Programmable Device Can Combine Glue Logic and Structured Designs
 - Enhanced Pin Locking Capability
 - Three Dedicated Clock Input Pins
 - Synchronous and Asynchronous Clocks
 - Programmable Output Slew Rate Control to Minimize Switching Noise
 - Flexible Pin Placement
 - Optimized Global Routing Pool Provides Global Interconnectivity
- **ispLSI/pLSI DEVELOPMENT TOOLS**
 - pDS[®] Software**
 - Easy to Use PC WindowsTM Interface
 - Boolean Logic Compiler
 - Manual Partitioning
 - Automatic Place and Route
 - Static Timing Table
 - pDS+TM Software**
 - Industry Standard, Third Party Design Environments
 - Schematic Capture, State Machine, HDL
 - Automatic Partitioning and Place and Route
 - Comprehensive Logic and Timing Simulation
 - PC and Workstation Platforms

Functional Block Diagram



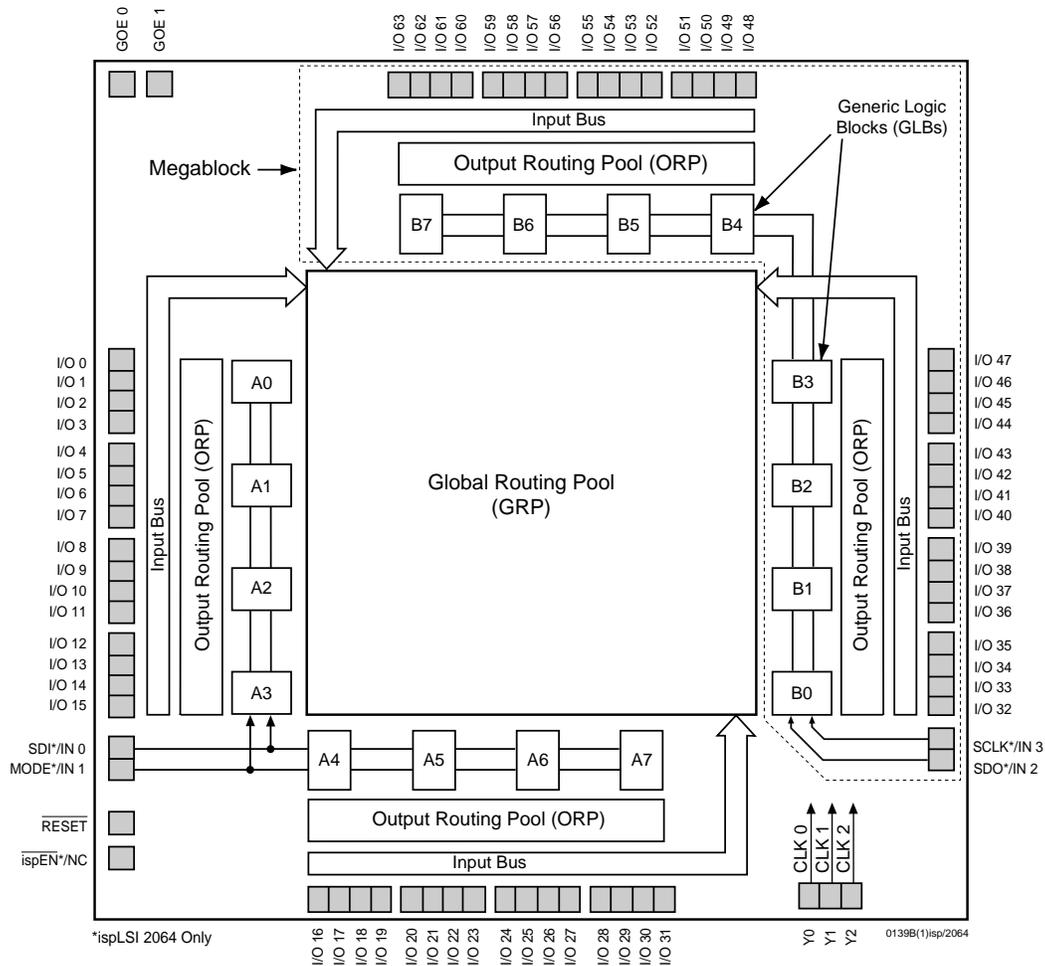
Description

The ispLSI and pLSI 2064 are High-Density Programmable Logic Devices. The devices contain 64 Registers, 64 Universal I/O pins, four Dedicated Input pins, three Dedicated Clock Input pins, two dedicated Global OE input pins and a Global Routing Pool (GRP). The GRP provides complete interconnectivity between all of these elements. The ispLSI 2064 features 5-Volt in-system programmability and in-system diagnostic capabilities. The ispLSI 2064 offers non-volatile "on-the-fly" reprogrammability of the logic, as well as the interconnect, to provide truly reconfigurable systems. It is architecturally and parametrically compatible to the pLSI 2064 device, but multiplexes four input pins to control in-system programming.

The basic unit of logic on the ispLSI and pLSI 2064 devices is the Generic Logic Block (GLB). The GLBs are labeled A0, A1...B7 (see figure 1). There are a total of 16 GLBs in the ispLSI and pLSI 2064 devices. Each GLB is made up of four macrocells. Each GLB has 18 inputs, a programmable AND/OR/Exclusive OR array, and four outputs which can be configured to be either combinatorial or registered. Inputs to the GLB come from the GRP and dedicated inputs. All of the GLB outputs are brought back into the GRP so that they can be connected to the inputs of any GLB on the device.

Functional Block Diagram

Figure 1. ispLSI and pLSI 2064 Functional Block Diagram



The devices also have 64 I/O cells, each of which is directly connected to an I/O pin. Each I/O cell can be individually programmed to be a combinatorial input, output or bi-directional I/O pin with 3-state control. The signal levels are TTL compatible voltages and the output drivers can source 4 mA or sink 8 mA. Each output can be programmed independently for fast or slow output slew rate to minimize overall output switching noise.

Eight GLBs, 32 I/O cells, two dedicated inputs and two ORPs are connected together to make a Megablock (see figure 1). The outputs of the eight GLBs are connected to

a set of 32 universal I/O cells by two ORPs. Each ispLSI and pLSI 2064 device contains two Megablocks.

The GRP has as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI and pLSI 2064 devices are selected using the dedicated clock pins. Three dedicated clock pins (Y0, Y1, Y2) or an asynchronous clock can be selected on a GLB basis. The asynchronous or Product Term clock can be generated in any GLB for its own clock.

Absolute Maximum Ratings ¹

Supply Voltage V_{CC}	-0.5 to +7.0V
Input Voltage Applied.....	-2.5 to $V_{CC} + 1.0V$
Off-State Output Voltage Applied	-2.5 to $V_{CC} + 1.0V$
Storage Temperature.....	-65 to 150°C
Case Temp. with Power Applied	-55 to 125°C
Max. Junction Temp. (T_J) with Power Applied	150°C

1. Stresses above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

DC Recommended Operating Condition

SYMBOL	PARAMETER		MIN.	MAX.	UNITS
V_{CC}	Supply Voltage	Commercial $T_A = 0^\circ\text{C to } +70^\circ\text{C}$	4.75	5.25	V
		Industrial $T_A = -40^\circ\text{C to } +85^\circ\text{C}$	4.5	5.5	V
V_{IL}	Input Low Voltage		0	0.8	V
V_{IH}	Input High Voltage		2.0	$V_{CC}+1$	V

Table 2 - 0005/2064

Capacitance ($T_A=25^\circ\text{C}$, $f=1.0\text{ MHz}$)

SYMBOL	PARAMETER	TYPICAL	UNITS	TEST CONDITIONS
C_1	Dedicated Input Capacitance	8	pf	$V_{CC} = 5.0V, V_{IN} = 2.0V$
C_2	I/O Capacitance	9	pf	$V_{CC} = 5.0V, V_{IO} = 2.0V$
C_3	Clock Capacitance	15	pf	$V_{CC} = 5.0V, V_Y = 2.0V$

Table 2 - 0006B

Data Retention Specifications

PARAMETER	MINIMUM	MAXIMUM	UNITS
Data Retention	20	–	Years
ispLSI Erase/Reprogram Cycles	10000	–	Cycles
pLSI Erase/Reprogram Cycles	100	–	Cycles

Table 2-0008A-isp

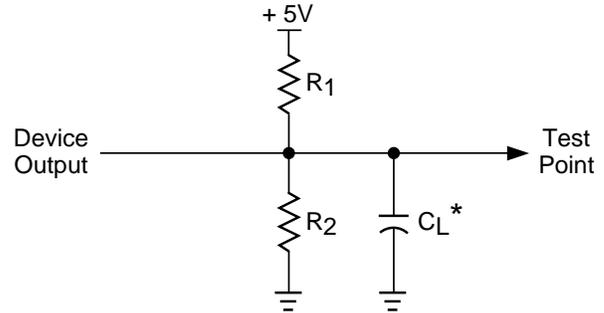
Switching Test Conditions

Input Pulse Levels	GND to 3.0V	
Input Rise and Fall Time 10% to 90%	-125	≤ 2 ns
	Others	≤ 3 ns
Input Timing Reference Levels	1.5V	
Output Timing Reference Levels	1.5V	
Output Load	See figure 2	

3-state levels are measured 0.5V from steady-state active level.

Table 2 - 0003/2064

Figure 2. Test Load



*CL includes Test Fixture and Probe Capacitance.

Output Load Conditions (see figure 2)

TEST CONDITION		R1	R2	CL
A		470Ω	390Ω	35pF
B	Active High	∞	390Ω	35pF
	Active Low	470Ω	390Ω	35pF
C	Active High to Z at $V_{OH}-0.5V$	∞	390Ω	5pF
	Active Low to Z at $V_{OL}+0.5V$	470Ω	390Ω	5pF

Table 2 - 0004A

DC Electrical Characteristics

Over Recommended Operating Conditions

SYMBOL	PARAMETER	CONDITION	MIN.	TYP. ³	MAX.	UNITS	
V_{OL}	Output Low Voltage	$I_{OL} = 8 \text{ mA}$	-	-	0.4	V	
V_{OH}	Output High Voltage	$I_{OH} = -4 \text{ mA}$	2.4	-	-	V	
I_{IL}	Input or I/O Low Leakage Current	$0V \leq V_{IN} \leq V_{IL}(\text{Max.})$	-	-	-10	μA	
I_{IH}	Input or I/O High Leakage Current	$3.5V \leq V_{IN} \leq V_{CC}$	-	-	10	μA	
I_{IL-isp}	ispEN Input Low Leakage Current	$0V \leq V_{IN} \leq V_{IL}$	-	-	-150	μA	
I_{IL-PU}	I/O Active Pull-Up Current	$0V \leq V_{IN} \leq V_{IL}$	-	-	-150	μA	
I_{OS}¹	Output Short Circuit Current	$V_{CC} = 5V, V_{OUT} = 0.5V$	-	-	-200	mA	
I_{CC}^{2, 4}	Operating Power Supply Current	$V_{IL} = 0.0V, V_{IH} = 3.0V$	Commercial	-	95	175	mA
		$f_{CLOCK} = 1 \text{ MHz}$	Industrial	-	95	-	mA

Table 2 - 0007Aisp/2064

- One output at a time for a maximum duration of one second. $V_{OUT} = 0.5V$ was selected to avoid test problems by tester ground degradation. Guaranteed but not 100% tested.
- Measured using four 16-bit counters.
- Typical values are at $V_{CC} = 5V$ and $T_A = 25^\circ C$.
- Maximum I_{CC} varies widely with specific device configuration and operating frequency. Refer to the Power Consumption section of this data sheet and Thermal Management section of this Data Book to estimate maximum I_{CC} .

External Timing Parameters

Over Recommended Operating Conditions

PARAMETER	TEST COND. ⁴	# ²	DESCRIPTION ¹	-125		-100		-80		UNITS
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
t _{pd1}	A	1	Data Propagation Delay, 4PT Bypass, ORP Bypass	–	7.5	–	10.0	–	15.0	ns
t _{pd2}	A	2	Data Propagation Delay	–	10.0	–	13.0	–	18.5	ns
f _{max}	A	3	Clock Frequency with Internal Feedback ³	125	–	100	–	81	–	MHz
f _{max} (Ext.)	–	4	Clock Frequency with External Feedback ($\frac{1}{t_{su2} + t_{co1}}$)	100	–	77	–	57	–	MHz
f _{max} (Tog.)	–	5	Clock Frequency, Max. Toggle	125	–	111	–	100	–	MHz
t _{su1}	–	6	GLB Reg. Setup Time before Clock, 4 PT Bypass	5.0	–	6.5	–	9.0	–	ns
t _{co1}	A	7	GLB Reg. Clock to Output Delay, ORP Bypass	–	4.0	–	5.0	–	6.5	ns
t _{h1}	–	8	GLB Reg. Hold Time after Clock, 4 PT Bypass	0.0	–	0.0	–	0.0	–	ns
t _{su2}	–	9	GLB Reg. Setup Time before Clock	6.0	–	8.0	–	11.0	–	ns
t _{co2}	–	10	GLB Reg. Clock to Output Delay	–	4.5	–	6.0	–	8.0	ns
t _{h2}	–	11	GLB Reg. Hold Time after Clock	0.0	–	0.0	–	0.0	–	ns
t _{r1}	A	12	Ext. Reset Pin to Output Delay	–	10.0	–	13.5	–	17.0	ns
t _{rw1}	–	13	Ext. Reset Pulse Duration	5.0	–	6.5	–	10.0	–	ns
t _{ptoen}	B	14	Product Term OE, Enable	–	12.0	–	15.0	–	18.0	ns
t _{ptoedis}	C	15	Product Term OE, Disable	–	12.0	–	15.0	–	18.0	ns
t _{goeen}	B	16	Global OE, Enable	–	7.0	–	9.0	–	12.0	ns
t _{goedis}	C	17	Global OE, Disable	–	7.0	–	9.0	–	12.0	ns
t _{wh}	–	18	External Synchronous Clock Pulse Duration, High	4.0	–	4.5	–	5.0	–	ns
t _{wl}	–	19	External Synchronous Clock Pulse Duration, Low	4.0	–	4.5	–	5.0	–	ns

Table 2 - 0030B/2064-130

1. Unless noted otherwise, all parameters use the GRP, 20 PTXOR path, ORP and Y0 clock.
2. Refer to Timing Model in this data sheet for further details.
3. Standard 16-bit counter using GRP feedback.
4. Reference Switching Test Conditions section.

Internal Timing Parameters¹

Over Recommended Operating Conditions

PARAMETER	# ²	DESCRIPTION	-125		-100		-80		UNITS
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
Inputs									
t_{io}	20	Input Buffer Delay	–	0.2	–	0.5	–	1.8	ns
t_{din}	21	Dedicated Input Delay	–	1.5	–	2.2	–	4.4	ns
GRP									
t_{grp}	22	GRP Delay	–	1.3	–	1.7	–	2.6	ns
GLB									
t_{4ptbp}	23	4 Product Term Bypass Comb. Path Delay	–	4.5	–	5.8	–	8.1	ns
t_{4ptbp}	24	4 Product Term Bypass Reg. Path Delay	–	5.0	–	5.8	–	6.8	ns
t_{1ptxor}	25	1 Product Term/XOR Path Delay	–	5.7	–	6.8	–	8.0	ns
t_{20ptxor}	26	20 Product Term/XOR Path Delay	–	6.0	–	7.3	–	8.8	ns
t_{xoradj}	27	XOR Adjacent Path Delay ³	–	6.5	–	8.0	–	9.8	ns
t_{gbp}	28	GLB Register Bypass Delay	–	0.5	–	0.5	–	1.3	ns
t_{gsu}	29	GLB Register Setup Time before Clock	0.8	–	1.2	–	1.4	–	ns
t_{gh}	30	GLB Register Hold Time after Clock	3.0	–	4.0	–	6.0	–	ns
t_{gco}	31	GLB Register Clock to Output Delay	–	0.2	–	0.3	–	0.4	ns
t_{gro}	32	GLB Register Reset to Output Delay	–	1.1	–	1.3	–	1.6	ns
t_{ptre}	33	GLB Product Term Reset to Register Delay	–	4.8	–	6.1	–	8.6	ns
t_{ptoe}	34	GLB Product Term Output Enable to I/O Cell Delay	–	7.3	–	8.6	–	9.0	ns
t_{ptck}	35	GLB Product Term Clock Delay	3.3	5.6	4.1	7.1	5.6	10.2	ns
ORP									
t_{orp}	36	ORP Delay	–	0.8	–	1.4	–	2.0	ns
t_{orpbp}	37	ORP Bypass Delay	–	0.3	–	0.4	–	0.5	ns
Outputs									
t_{ob}	38	Output Buffer Delay	–	1.2	–	1.6	–	2.0	ns
t_{sl}	39	Output Slew Limited Delay Adder	–	10.0	–	10.0	–	10.0	ns
t_{oen}	40	I/O Cell OE to Output Enabled	–	3.2	–	4.2	–	4.6	ns
t_{odis}	41	I/O Cell OE to Output Disabled	–	3.2	–	4.2	–	4.6	ns
t_{goe}	42	Global Output Enable	–	3.8	–	4.8	–	7.4	ns
Clocks									
t_{gy0}	43	Clock Delay, Y0 to Global GLB Clock Line (Ref. clock)	2.3	2.3	2.7	2.7	3.6	3.6	ns
t_{gy1/2}	44	Clock Delay, Y1 or Y2 to Global GLB Clock Line	2.3	2.3	2.7	2.7	3.6	3.6	ns
Global Reset									
t_{gr}	45	Global Reset to GLB	–	6.9	–	9.2	–	11.4	ns

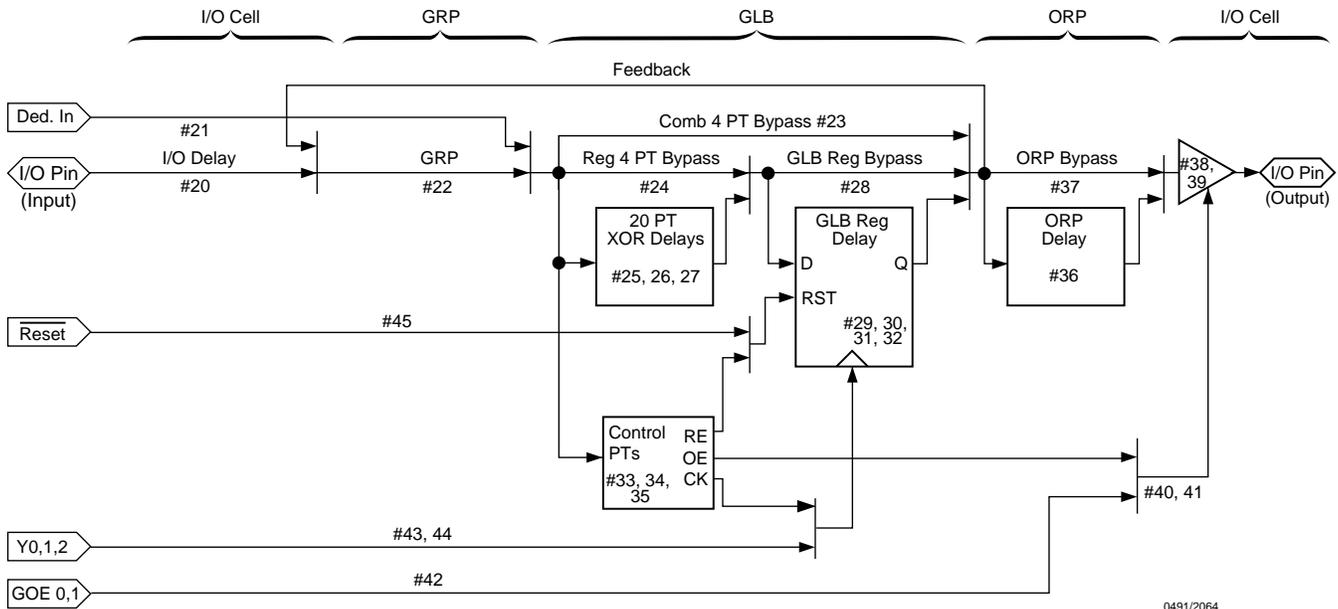
1. Internal Timing Parameters are not tested and are for reference only.

Table 2- 0036C/2064-130

2. Refer to Timing Model in this data sheet for further details.

3. The XOR adjacent path can only be used by hard macros.

ispLSI and pLSI 2064 Timing Model



Derivations of t_{su} , t_h and t_{co} from the Product Term Clock¹

$$\begin{aligned}
 t_{su} &= \text{Logic} + \text{Reg } s_u - \text{Clock (min)} \\
 &= (t_{io} + t_{grp} + t_{20ptxor}) + (t_{gsu}) - (t_{io} + t_{grp} + t_{ptck(min)}) \\
 &= (\#20 + \#22 + \#26) + (\#29) - (\#20 + \#22 + \#35) \\
 3.5 \text{ ns} &= (0.2 + 1.3 + 6.0) + (0.8) - (0.2 + 1.3 + 3.3) \\
 \\
 t_h &= \text{Clock (max)} + \text{Reg } h - \text{Logic} \\
 &= (t_{io} + t_{grp} + t_{ptck(max)}) + (t_{gh}) - (t_{io} + t_{grp} + t_{20ptxor}) \\
 &= (\#20 + \#22 + \#35) + (\#30) - (\#20 + \#22 + \#26) \\
 2.6 \text{ ns} &= (0.2 + 1.3 + 5.6) + (3.0) - (0.2 + 1.3 + 6.0) \\
 \\
 t_{co} &= \text{Clock (max)} + \text{Reg } c_o + \text{Output} \\
 &= (t_{io} + t_{grp} + t_{ptck(max)}) + (t_{gco}) + (t_{orp} + t_{ob}) \\
 &= (\#20 + \#22 + \#35) + (\#31) + (\#36 + \#38) \\
 9.4 \text{ ns} &= (0.2 + 1.3 + 5.6) + (0.2) + (0.8 + 1.2)
 \end{aligned}$$

Table 2- 0042A-2064

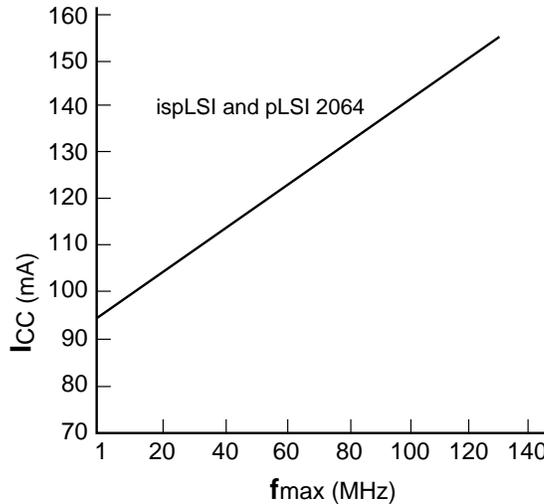
Note: Calculations are based upon timing specifications for the ispLSI and pLSI 2064-125L.

Power Consumption

Power Consumption in the ispLSI and pLSI 2064 device depends on two primary factors: the speed at which the device is operating and the number of Product Terms

used. Figure 3 shows the relationship between power and operating speed.

Figure 3. Typical Device Power Consumption vs fmax



Notes: Configuration of Four 16-bit Counters
Typical Current at 5V, 25° C

ICC can be estimated for the ispLSI and pLSI 2064 using the following equation:

$$I_{CC}(mA) = 38 + (\# \text{ of PTs} * 0.33) + (\# \text{ of nets} * \text{Max freq} * 0.007)$$

Where:

- # of PTs = Number of Product Terms used in design
- # of nets = Number of Signals used in device
- Max freq = Highest Clock Frequency to the device (in MHz)

The ICC estimate is based on typical conditions (VCC = 5.0V, room temperature) and an assumption of 2 GLB loads on average exists. These values are for estimates only. Since the value of ICC is sensitive to operating conditions and the program in the device, the actual ICC should be verified.

0127A-64-80isp/2000

In-System Programmability

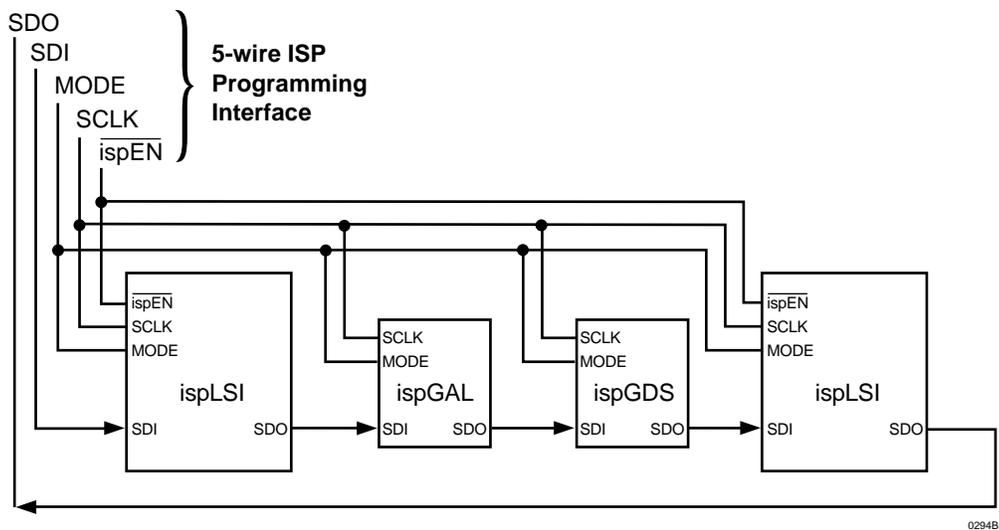
The ispLSI devices are the in-system programmable versions of the Lattice Semiconductor high density programmable Large Scale Integration (pLSI) devices. By integrating all the high voltage programming circuitry on-chip, programming can be accomplished by simply shifting data into the device. Once the function is programmed, the non-volatile E²CMOS cells will not lose the pattern even when the power is turned off.

All necessary programming is done via five TTL level logic interface signals. These five signals are fed into the on-chip programming circuitry where a state machine

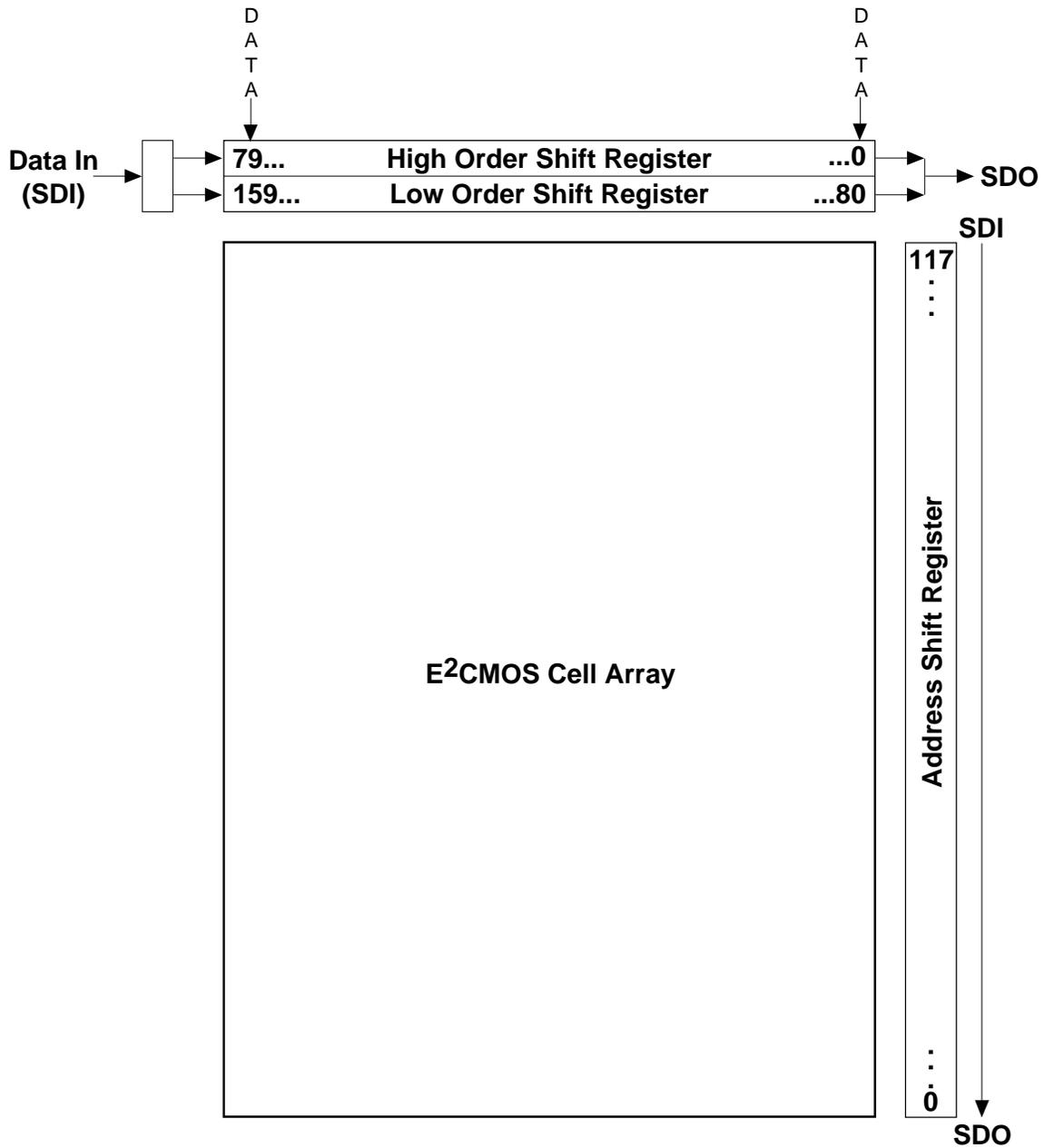
controls the programming. The simple signals for the interface include isp Enable (ispEN), Serial Data In (SDI), Serial Data Out (SDO), Serial Clock (SCLK) and Mode (MODE) control. Figure 4 illustrates the block diagram of one possible scheme of the programming interface for the ispLSI devices. For details on the operation of the internal state machine and programming of the device, please refer to the ISP Architecture and Programming section of this Data Book.

The device identifier for the ispLSI 2064 is 0001 0010 (12 hex). This code is the unique device identifier which is generated when a read ID command is performed.

Figure 4. ISP Programming Interface



ispLSI 2064 Shift Register Layout



Note: A logic "1" in the address shift register enables the row for programming or verification. A logic "0" disables it.

Pin Description

NAME	PLCC PIN NUMBERS	DESCRIPTION
I/O 0 - I/O 3 I/O 4 - I/O 7 I/O 8 - I/O 11 I/O 12 - I/O 15 I/O 16 - I/O 19 I/O 20 - I/O 23 I/O 24 - I/O 27 I/O 28 - I/O 31 I/O 32 - I/O 35 I/O 36 - I/O 39 I/O 40 - I/O 43 I/O 44 - I/O 47 I/O 48 - I/O 51 I/O 52 - I/O 55 I/O 56 - I/O 59 I/O 60 - I/O 63	26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18	Input/Output Pins — These are the general purpose I/O pins used by the logic array.
GOE 0, GOE 1	67, 84	Global Output Enable input pins.
Y0, Y1, Y2 $\overline{\text{RESET}}$	20, 66, 63 24	Dedicated Clock input. This clock input is connected to one of the clock inputs of all the GLBs in the device. Active Low (0) Reset pin which resets all registers in the device.
$\overline{\text{ispEN}}^{**}/\text{NC}$ SDI*/IN 0 MODE*/IN 1 SDO*/IN 2 SCLK*/IN 3 NC	23 25 42 44 61 2, 19, 62	Input — Dedicated in-system programming enable pin. This pin is brought low to enable the programming mode. When low, the MODE, SDI, SDO and SCLK controls become active. Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the ISP state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated pin input. Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a pin to control the operation of the ISP state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. Output/Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. Input — This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the Serial Shift Register. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. These pins are not used.
GND VCC	1, 22, 43, 64 21, 65	Ground (GND) Vcc

* ispLSI 2064 Only

Table 2- 0002A-08isp/2064

** $\overline{\text{ispEN}}$ for ispLSI 2064 only; NC for pLSI 2064, must be left floating or tied to Vcc, must not be grounded or tied to any other signal.

Pin Description

Name	TQFP Pin Numbers	Description
I/O 0 - I/O 3 I/O 4 - I/O 7 I/O 8 - I/O 11 I/O 12 - I/O 15 I/O 16 - I/O 19 I/O 20 - I/O 23 I/O 24 - I/O 27 I/O 28 - I/O 31 I/O 32 - I/O 35 I/O 36 - I/O 39 I/O 40 - I/O 43 I/O 44 - I/O 47 I/O 48 - I/O 51 I/O 52 - I/O 55 I/O 56 - I/O 59 I/O 60 - I/O 63	17, 18, 19, 20, 21, 22, 23, 28, 29, 30, 31, 32, 33, 34, 35, 36, 40, 41, 42, 43, 44, 45, 46, 47, 48, 53, 54, 55, 56, 57, 58, 59, 67, 68, 69, 70, 71, 72, 73, 78, 79, 80, 81, 82, 83, 84, 85, 86, 90, 91, 92, 93, 94, 95, 96, 97, 98, 3, 4, 5, 6, 7, 8, 9	Input/Output Pins - These are the general purpose I/O pins used by the logic array.
GOE 0, GOE 1	66, 87	Global Output Enable input pins.
Y0, Y1, Y2 $\overline{\text{RESET}}$	11, 65, 62 15	Dedicated Clock input. This clock input is connected to one of the clock inputs of all of the GLBs on the device. Active Low (0) Reset pin which resets all of the registers in the device.
$\overline{\text{ispEN}}^{**}/\text{NC}$ SDI*/IN 0 MODE*/IN 1 SDO*/IN 2 SCLK*/IN 3 NC	14 16 37 39 60 1, 2, 10, 24, 25, 26, 27, 49, 50, 51, 52, 61, 74, 75, 76, 77, 89, 99, 100	Input – Dedicated in-system programming enable input pin. This pin is brought low to enable the programming mode. The MODE, SDI, SDO and SCLK controls become active. Input – This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the ISP state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. Input – This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a pin to control the operation of the ISP state machine. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. Output/Input – This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. Input – This pin performs two functions. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the Serial Shift Register. When $\overline{\text{ispEN}}$ is high, it functions as a dedicated input pin. These pins are not used.
GND V _{CC}	13, 38, 63, 88 12, 64	Ground (GND) V _{CC}

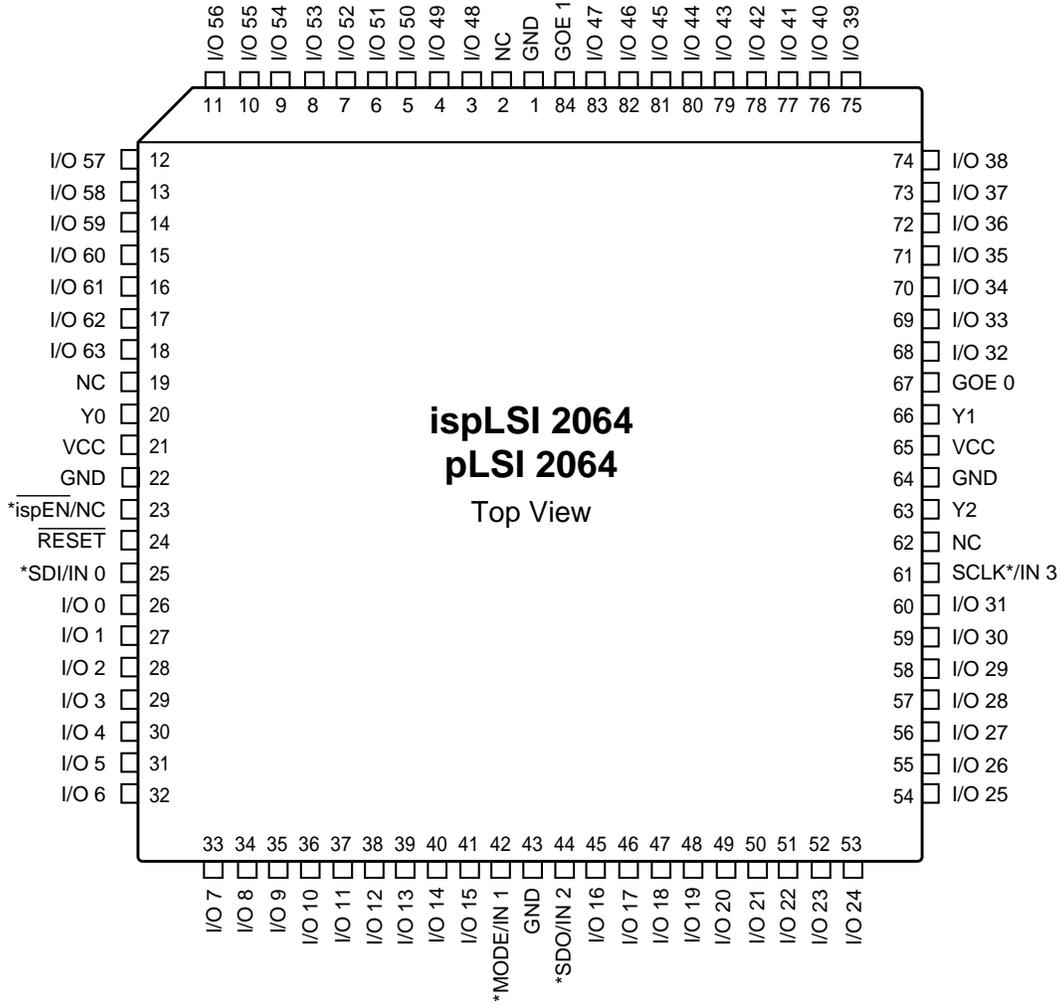
* ispLSI 2064 Only

** $\overline{\text{ispEN}}$ for ispLSI 2064 only; NC for pLSI 2064, must be left floating or tied to V_{CC}, must not be grounded or tied to any other signal.

Table 2- 0002-2064.eps

Pin Configuration

ispLSI and pLSI 2064 84-pin PLCC

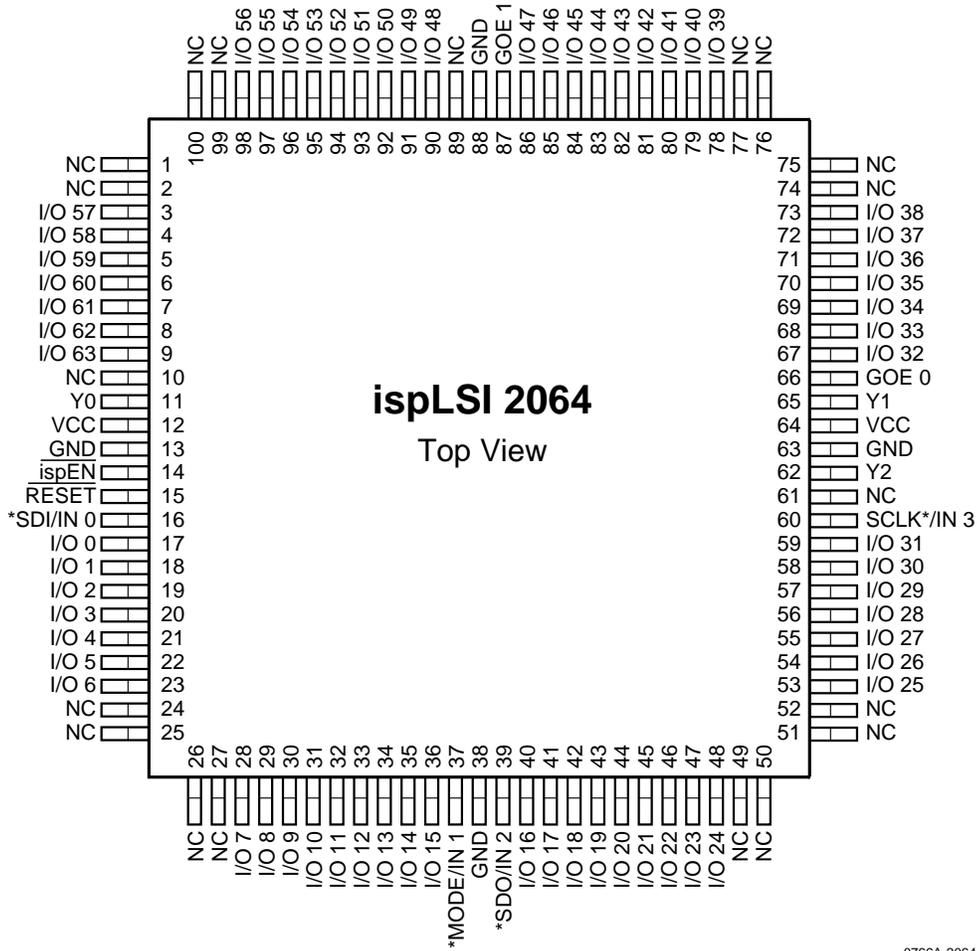


*Pins have dual function capability for ispLSI 2064 only (except pin 23, which is ispEN only).

0123A/2064

Pin Configuration

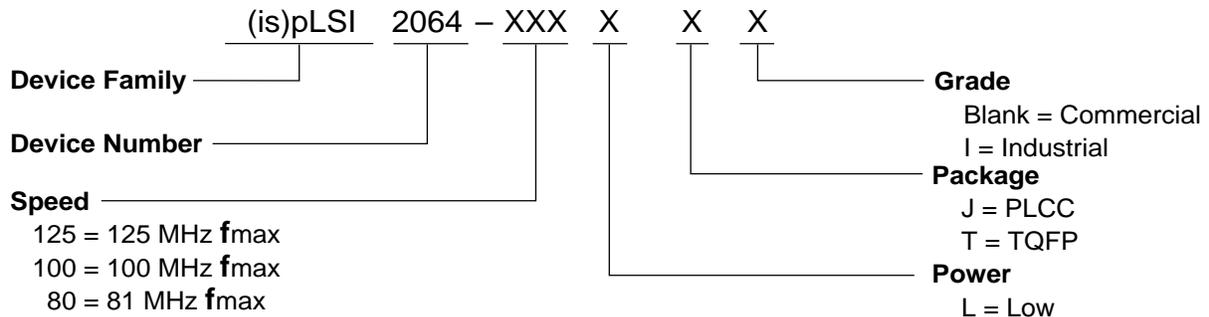
ispLSI 2064 100-pin TQFP



0766A-2064-isp

*Pins have dual function capability.

Part Number Description



212-80Bisp/2000

ispLSI and pLSI 2064 Ordering Information

COMMERCIAL

Device Family	f_{max} (MHz)	t_{pd} (ns)	Ordering Number	Package
ispLSI	125	7.5	ispLSI 2064-125LJ	84-Pin PLCC
	125	7.5	ispLSI 2064-125LT	100-Pin TQFP
	100	10	ispLSI 2064-100LJ	84-Pin PLCC
	100	10	ispLSI 2064-100LT	100-Pin TQFP
	81	15	ispLSI 2064-80LJ	84-Pin PLCC
	81	15	ispLSI 2064-80LT	100-Pin TQFP
pLSI	125	7.5	pLSI 2064-125LJ	84-Pin PLCC
	100	10	pLSI 2064-100LJ	84-Pin PLCC
	81	15	pLSI 2064-80LJ	84-Pin PLCC

Table 2- 0041A-08isp/2000

INDUSTRIAL

Device Family	f_{max} (MHz)	t_{pd} (ns)	Ordering Number	Package
ispLSI	81	15	ispLSI 2064-80LJI	84-Pin PLCC
	81	15	ispLSI 2064-80LTI	100-Pin TQFP

Table 2- 0041B-08isp/2000



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